

## ● TSOT-26 Power Dissipation 105°C

Power dissipation data for the TSOT-26 is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as the reference data taken in the following condition.

### 1. Measurement Condition

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: The board using 4 copper layer.

(76.2mm×114.3mm...Area: about 8700mm<sup>2</sup>)

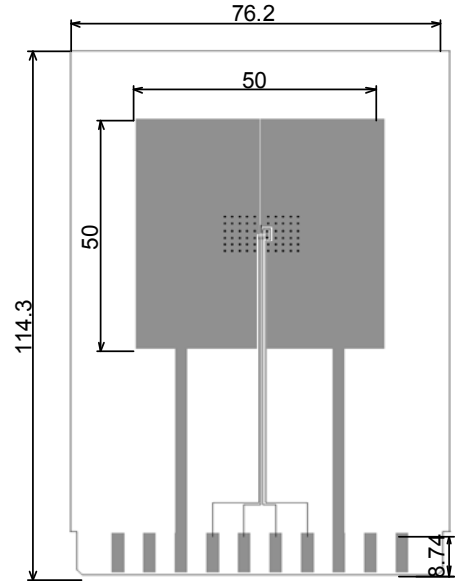
Each copper layer are as follows.

- 1st layer : 25mm×50mm\_Connected to 2 pin.  
25mm×50mm\_Connected to 3 pin.
- 2nd layer : 35mm×70mm\_Connected to 2 pin.  
35mm×70mm\_Connected to 3 pin.
- 3rd layer : 35mm×70mm\_Connected to 2 pin.  
35mm×70mm\_Connected to 3 pin.
- 4th layer : 25mm×50mm\_Connected to 2 pin.  
25mm×50mm\_Connected to 3 pin.

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: φ0.2mm: 60 pcs



Evaluation Board (Unit: mm)

### 2. Power Dissipation vs. Ambient Temperature

Board Mount (T<sub>j</sub> max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1300	76.92
105	260	

